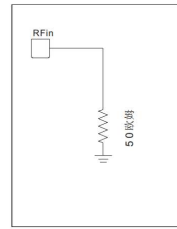


Performance

- Frequency: DC-4GHz
- Input Return Loss: -15dB
- Power Handling: 10W/CW
- Chip size: 1800*1000*100μm

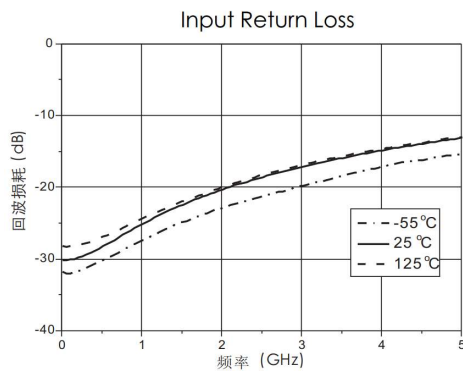
Function Diagram



Electrical Specifications (TA=+25°C, 50Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range		DC-4		GHz
Input Return Loss	-	15	-	dB
Power Handling	-	-	10	W

Test Curves (Die chip testing)



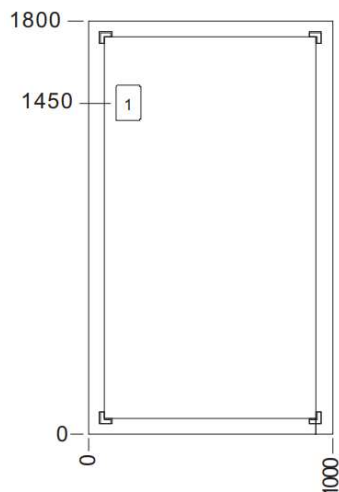
Absolute Max Ratings

Max Handling Power	10W
Junction Temperature	225°C
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Static Protection Grade	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Size

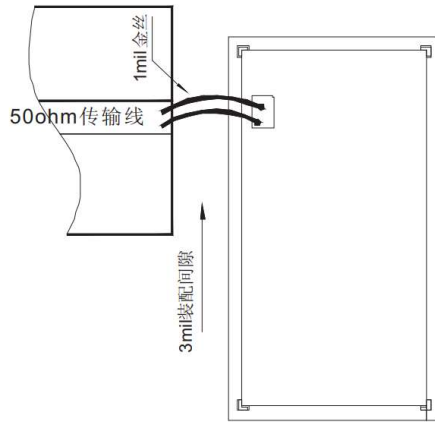


Note:

Unit: μm

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated: 100*500μm
4. Don't bonding on thru holes
5. Tolerance: ±50μm

Assembly Drawing



Typical assemble gap: 0.076~0.152mm (3~6mils)

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port 50 ohm impedance
	GND	Bottom side of chip must be grounded